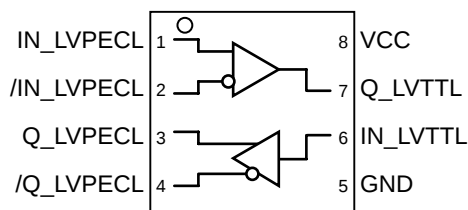


PACKAGE/ORDERING INFORMATION**8-Pin MLF™****Ultra-Small Outline (2mm × 2mm)****Ordering Information**

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY89328LMITR	MLF-8	Industrial	HEP28	Sn-Pb
SY89328LMGTR	MLF-8	Industrial	HEP28 with Pb-Free bar-line indicator	Pb-Free NiPdAu

PIN DESCRIPTION

Pin Number	Pin Name	Type	Pin Function
1, 2	IN_LVPECL, /IN_LVPECL	100k ECL Input	Differential LVPECL Input: Includes internal 75kΩ pull-down resistor on internal 75kΩ pull-up and pull-down resistors on /IN. See "Input Interface Applications" section for single-ended inputs.
7	Q_LVTTL	LVTTL Output	Single-ended LVTTL Output: Translated from LVPECL input. Q_LVTTL output will default LOW with IN_LVPECL and /IN_LVPECL inputs left open.
6	IN_LVTTL	LVTTL Input	Single-ended LVTTL Input.
3, 4	Q_LVPECL, /Q_LVPECL	100k ECL Output	Differential LVPECL Output: Translated from LVTTL input. See "Output Interface Applications" section for recommendations on terminations.
8	VCC	VCC Power	Positive Power Supply: Bypass with 0.1μF//0.01μF low ESR capacitors.
5	GND, Exposed Pad	Ground	GND and exposed pad must be tied to ground plane.

Absolute Maximum Ratings(Note 1)

Supply Voltage (V_{CC})	–0.5V to +3.8V
Input Voltage (V_{IN})	–0.5V to V_{CC}
LVPECL Output Current (I_{OUT})	
Continuous	50mA
Surge	100mA
Input Current	
Source or sink current on IN, /IN	±50mA
Lead Temperature (soldering, 20 sec.)	+260°C
Storage Temperature (T_S)	–65°C to +150°C

Operating Ratings(Note 2)

Supply Voltage (V_{CC})	3.0V to 3.6V
Ambient Temperature (T_A)	–40°C to +85°C
Package Thermal Resistance, Note 3	
MLF™ (θ_{JA})	
Still-Air	93°C/W
500lfpm	87°C/W
MLF™ (Ψ_{JB})	
Junction-to-Board	60°C/W

Note 1. Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to ABSOLUTE MAXIMUM RATING conditions for extended periods may affect device reliability.

Note 2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.

Note 3. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the devices most negative potential on the PCB.

DC ELECTRICAL CHARACTERISTICS(Note 4)

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{CC}	Power Supply Voltage		3.0	3.3	3.6	V
I_{CC}	Power Supply Current	Max V_{CC} , No Load		22	40	mA

LVPECL DC ELECTRICAL CHARACTERISTICS(Note 4)

$V_{CC} = +3.3V \pm 10\%$ and $V_{EE} = 0V$; $R_L = 50\Omega$ to $V_{CC} - 2V$; $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, unless otherwise noted.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{OH}	Output HIGH Voltage		$V_{CC} - 1.145$	$V_{CC} - 1.020$	$V_{CC} - 0.895$	V
V_{OL}	Output LOW Voltage		$V_{CC} - 1.945$	$V_{CC} - 1.820$	$V_{CC} - 1.695$	V
V_{IH}	Input HIGH Voltage		$V_{CC} - 1.225$		$V_{CC} - 0.880$	V
V_{IL}	Input LOW Voltage		$V_{CC} - 1.945$		$V_{CC} - 1.625$	V
V_{CMR}	LVPECL Common Mode Range		1.2		V_{CC}	V
I_{IH}	Input HIGH Current	$V_{IN} = 3.46V$			150	μA
I_{IL}	Input LOW Current	IN	0.5			μA
		/IN	–300			μA

Note 4. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

LVTTTL DC ELECTRICAL CHARACTERISTICS(Note 5)

$V_{CC} = +3.3V \pm 10\%$; $C_L = 20pF$, $T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise noted.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{OH}	Output HIGH Voltage	$I_{OH} = -3mA$	2.0	—	—	V
V_{OL}	Output LOW Voltage	$I_{OH} = -24mA$	—	—	0.5	V
V_{IH}	Input HIGH Voltage		2.0	—	—	V
V_{IL}	Input LOW Voltage		—	—	0.8	V
V_{IK}	Input Clamp Voltage	$I_{IK} = -18mA$	—	—	-1.2	V
I_{IH}	Input HIGH Current	$V_{IN} = 2.7V$	—	—	20	μA
		$V_{IN} = V_{CC}$	—	—	100	μA
I_{IL}	Input LOW Current	$V_{IN} = 0.5V$	—	—	-0.2	μA
$I_{OUT(SC)}$	LVTTTL Output Short-Circuit Current	$V_{OUT} = 0V$	-275	—	-80	mA

AC ELECTRICAL CHARACTERISTICS

$V_{CC} = +3.3V \pm 10\%$. $T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise noted.

Symbol	Parameter	Condition	Min	Typ	Max	Units
f_{MAX}	Maximum Frequency LVPECL	Note 6	700	—	—	MHz
	LVTTTL	Note 7	275	350	—	MHz
t_{pd}	Propagation Delay IN_LVPECL-to-Q_LVTTTL	Note 7	1.5	—	2.5	ns
	IN_LVTTTL-to-Q_LVPECL	Note 6	100	400	600	ps
V_{PP}	LVPECL Input Voltage Swing (Single-Ended)	Note 8	100	—	—	mV
t_{DC}	Duty Cycle		45	50	55	%
t_{Jitter}	Cycle-toCycle Jitter	Note 9			<1	μs_{RMS}
	Total Jitter	Note 10			20	μs_{PP}
t_r, t_f	LVPECL Output Rise/Fall Times (20% to 80%)	At full output swing, Note 5	200	—	500	ns
	LVTTTL Output Rise/Fall Times (10% to 90%)	At full output swing, Note 6	0.5	—	1.0	ns

Note 5. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

Note 6. $R_L = 50\Omega$ to $V_{CC} - 2V$

Note 7. $C_L = 20pF$

Note 8. V_{PP} (min) is the minimum input swing for which AC parameters are guaranteed.

Note 9. Cycle-to-cycle jitter definition: the variation of periods between adjacent cycles, $T_n - T_{n-1}$, where T is the time between rising edges of the output signal.

Note 10. Total jitter definition: with an ideal clock input of frequency $\leq f_{MAX}$, no more than one output edge in 10^{12} output edge will deviate by more than the specified peak-to-peak jitter value.

LVPECL INPUT INTERFACE APPLICATIONS

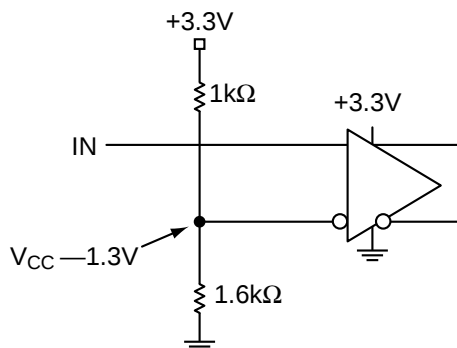


Figure 1. Single-Ended Input
(Terminating unused input)

LVPECL OUTPUT INTERFACE APPLICATIONS

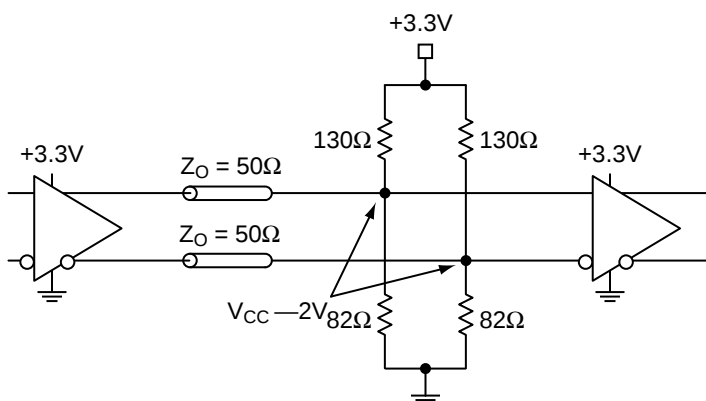


Figure 2a. Parallel Thevenin-Equivalent
Termination

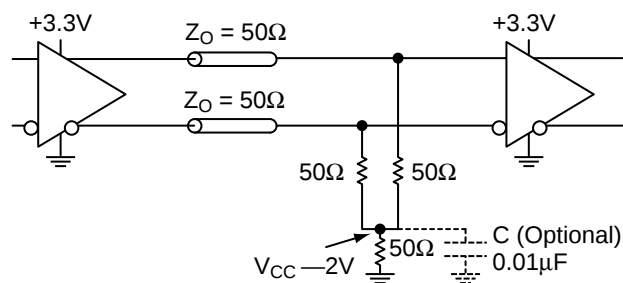


Figure 2b. Three Resistor
"Y Termination"

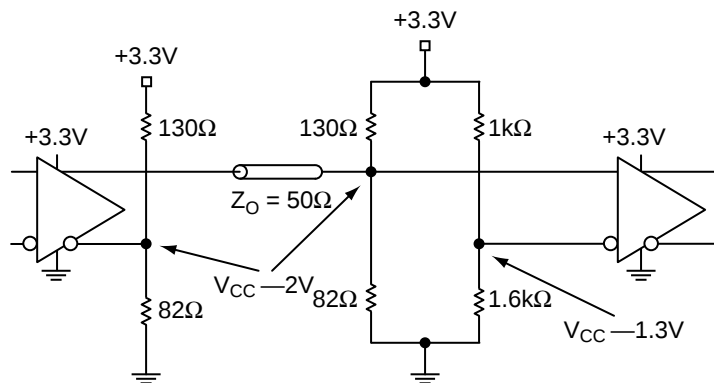
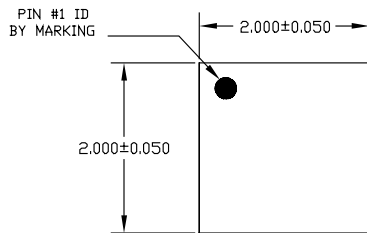
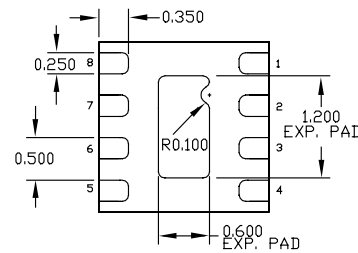


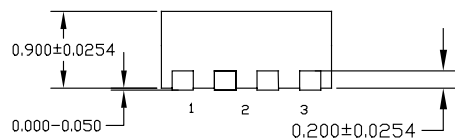
Figure 2c. Terminating Unused I/O

8 LEAD ULTRA-SMALL EPAD-MicroLeadFrame™ (MLF-8)

TOP VIEW

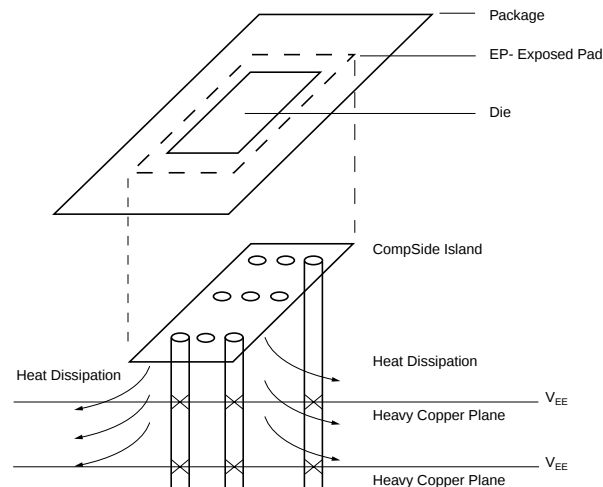


BOTTOM VIEW



SIDE VIEW

- NOTE:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
 2. MAX. PACKAGE WARPAGE IS 0.05 mm.
 3. MAXIMUM ALLOWABLE BURRS IS 0.076 mm IN ALL DIRECTIONS.
 4. PIN #1 ID ON TOP WILL BE LASER/INK MARKED.

**PCB Thermal Consideration for 8-Pin MLF™ Package****Package Notes:**

- Note 1.** Package meets Level 2 qualification.
Note 2. All parts are dry-packaged before shipment.
Note 3. Exposed pads must be soldered to a ground for proper thermal management.

MICREL, INC. 2180 FORTUNE DRIVE SAN JOSE, CA 95131 USA

TEL + 1 (408) 944-0800 FAX + 1 (408) 474-1000 WEB <http://www.micrel.com>

The information furnished by Micrel in this datasheet is believed to be accurate and reliable. However, no responsibility is assumed by Micrel for its use. Micrel reserves the right to change circuitry and specifications at any time without notification to the customer.

Micrel Products are not designed or authorized for use as components in life support appliances, devices or systems where malfunction of a product can reasonably be expected to result in personal injury. Life support devices or systems are devices or systems that (a) are intended for surgical implant into the body or (b) support or sustain life, and whose failure to perform can be reasonably expected to result in a significant injury to the user. A Purchaser's use or sale of Micrel Products for use in life support appliances, devices or systems is at Purchaser's own risk and Purchaser agrees to fully indemnify Micrel for any damages resulting from such use or sale.

© 2005 Micrel, Incorporated.